HAT2201WP

Silicon N Channel Power MOS FET
Power Switching

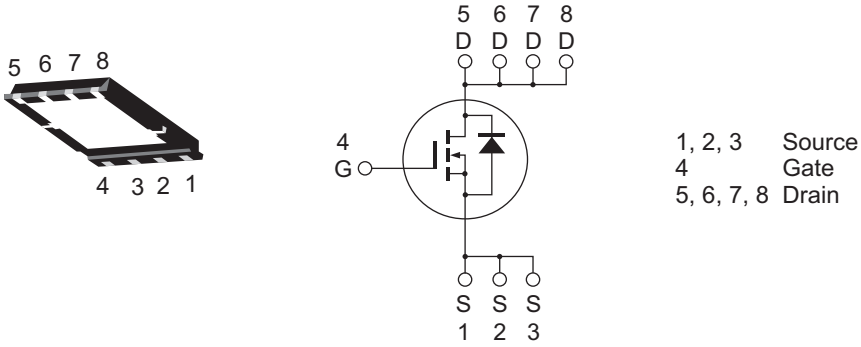
REJ03G1679-0300
Rev.3.00
May 27, 2008

Features

- Capable of 8 V gate drive
- Low drive current
- High density mounting
- Low on-resistance
  $R_{DS(on)}$ = 34 mΩ typ. (at V_{GS} = 10 V)

Outline

RENESAS Package code: PWSN0008DA-A
(Package name: WPAK)



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Ratings	Unit
Drain to source voltage	V_{DSS}	100	V
Gate to source voltage	V_{GSS}	±20	V
Drain current	I_D	15	A
Drain peak current	$I_{D(pulse)}$ Note1	60	A
Body-drain diode reverse drain current	I_{DR}	15	A
Avalanche current	I_{AP} Note 2	15	A
Avalanche energy	E_{AR} Note 2	22.5	mJ
Channel dissipation	Pch Note3	15	W
Channel to case thermal Impedance	θch-c Note3	8.33	°C/W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	–55 to +150	°C

Notes: 1. PW ≤ 10 µs, duty cycle ≤ 1%
2. Value at Tch = 25°C, Rg ≥ 50 Ω
3. Tc = 25°C

Electrical Characteristics

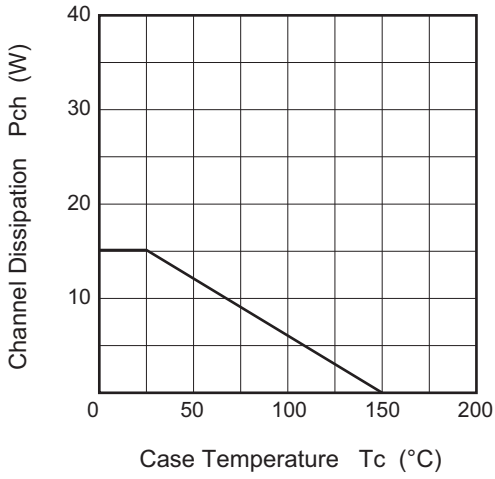
(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	100	—	—	V	I_D = 10 mA, V_{GS} = 0
Gate to source leak current	I_{GSS}	—	—	±0.1	µA	V_{GS} = ±20 V, V_{DS} = 0
Zero gate voltage drain current	I_{DSS}	—	—	1	µA	V_{DS} = 100 V, V_{GS} = 0
Gate to source cutoff voltage	$V_{GS(off)}$	3.5	—	5.0	V	V_{DS} = 10 V, I_D = 1 mA
Static drain to source on state resistance	$R_{DS(on)}$	—	34	43	mΩ	I_D = 7.5 A, V_{GS} = 10 V Note4
	$R_{DS(on)}$	—	35	49	mΩ	I_D = 7.5 A, V_{GS} = 8 V Note4
Forward transfer admittance	$\|y_{fs}\|$	12	20	—	S	I_D = 7.5 A, V_{DS} = 10 V Note4
Input capacitance	Ciss	—	1450	—	pF	V_{DS} = 10 V
Output capacitance	Coss	—	180	—	pF	V_{GS} = 0
Reverse transfer capacitance	Crss	—	65	—	pF	f = 1 MHz
Gate resistance	Rg	—	0.9	—	Ω	
Total gate charge	Qg	—	21	—	nc	V_{DD} = 50 V
Gate to source charge	Qgs	—	7.6	—	nc	V_{GS} = 10 V
Gate to drain charge	Qgd	—	5.2	—	nc	I_D = 15 A
Turn-on delay time	$t_{d(on)}$	—	18	—	ns	V_{GS} = 10 V, I_D = 7.5 A
Rise time	t_r	—	3	—	ns	V_{DD} ≅ 30 V
Turn-off delay time	$t_{d(off)}$	—	33	—	ns	R_L = 4 Ω
Fall time	t_f	—	4.1	—	ns	Rg = 4.7 Ω
Body–drain diode forward voltage	V_{DF}	—	0.84	1.10	V	I_F = 15 A, V_{GS} = 0 Note4
Body–drain diode reverse recovery time	t_{rr}	—	45	—	ns	I_F = 15 A, V_{GS} = 0 di_F/dt = 100 A/µs

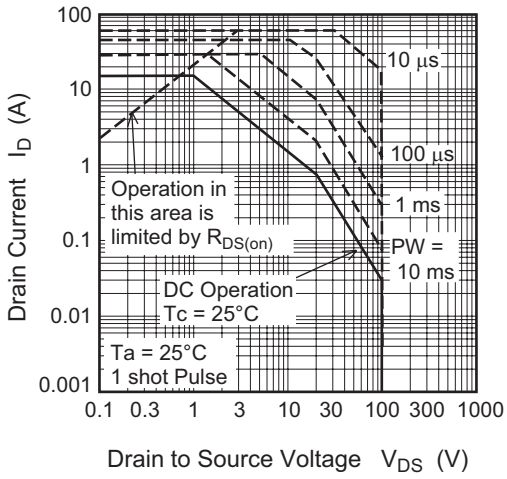
Notes: 4. Pulse test

Main Characteristics

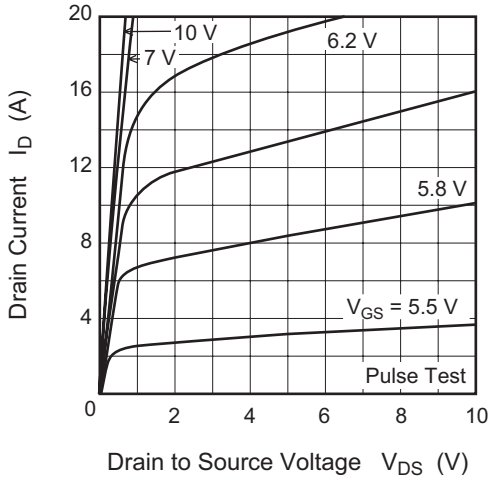
Power vs. Temperature Derating



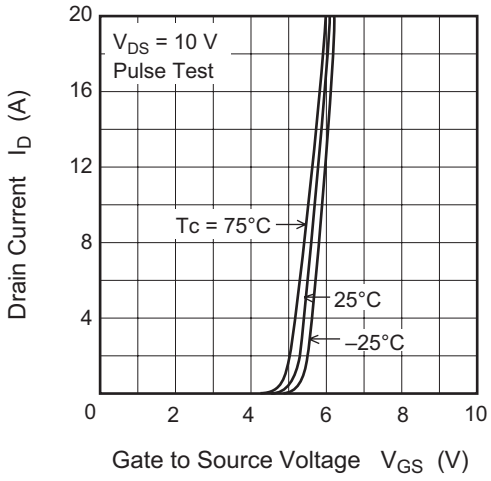
Maximum Safe Operation Area



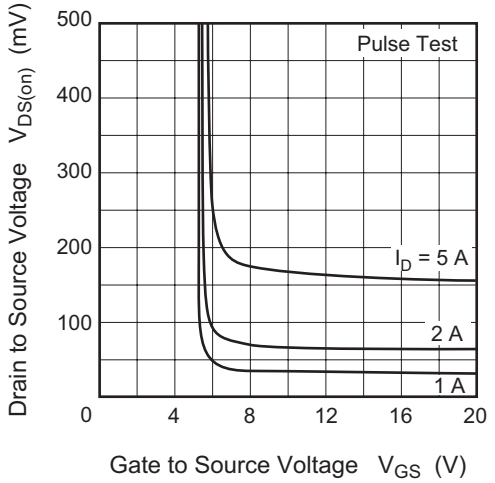
Typical Output Characteristics



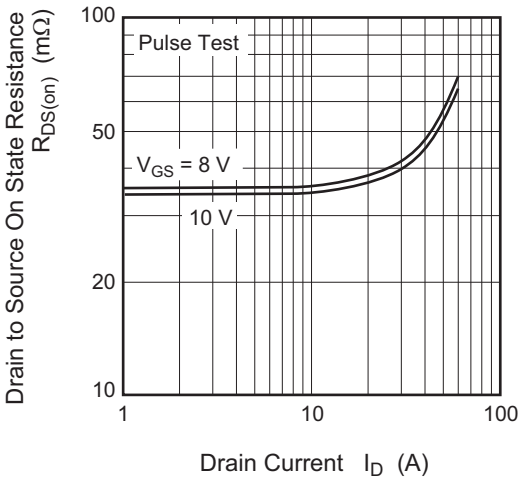
Typical Transfer Characteristics



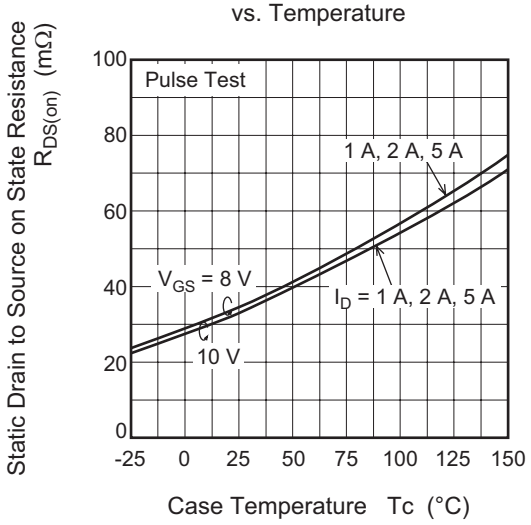
Drain to Source Saturation Voltage vs. Gate to Source Voltage



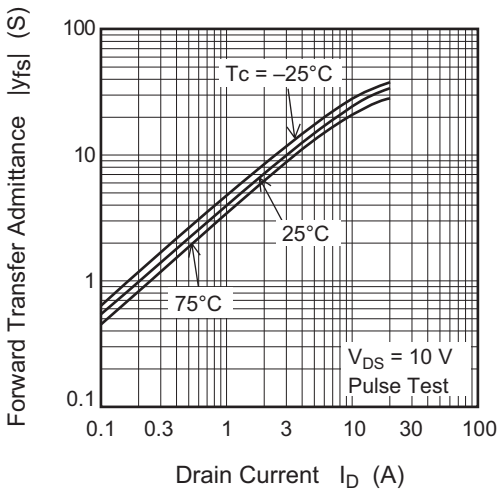
Static Drain to Source on State Resistance vs. Drain Current



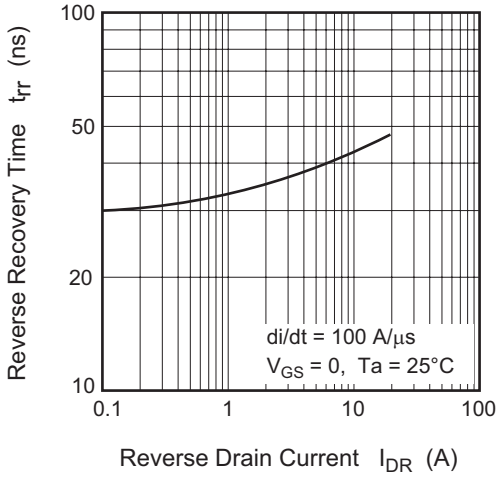
Static Drain to Source on State Resistance vs. Temperature



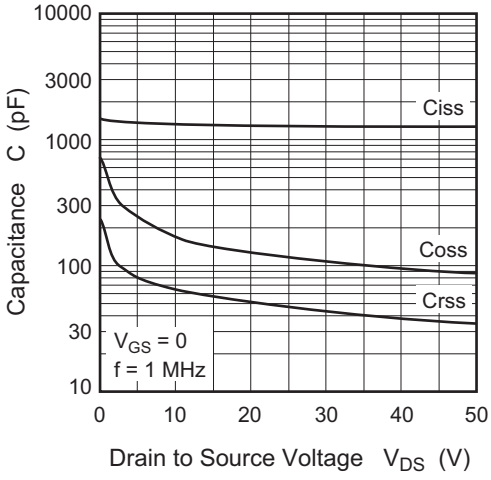
Forward Transfer Admittance vs. Drain Current



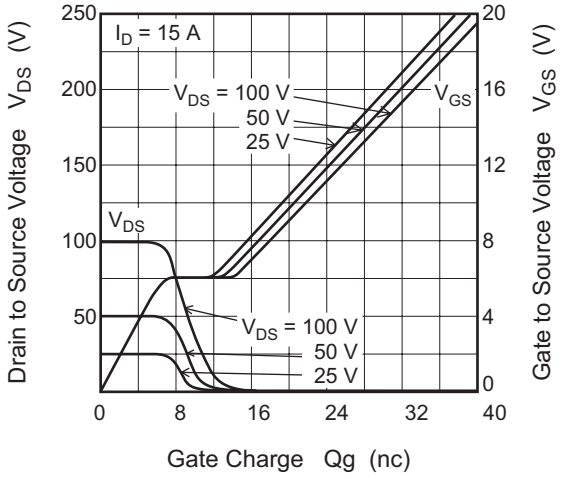
Body–Drain Diode Reverse Recovery Time



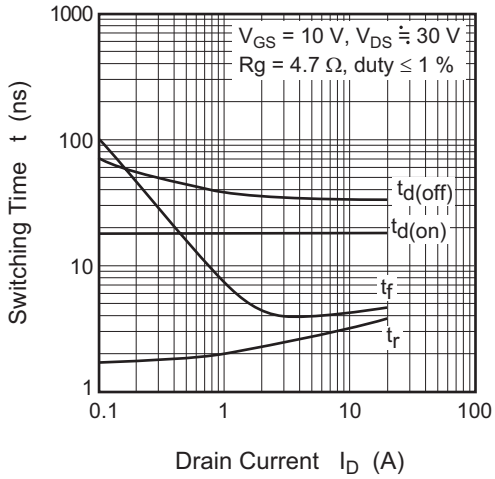
Typical Capacitance vs. Drain to Source Voltage



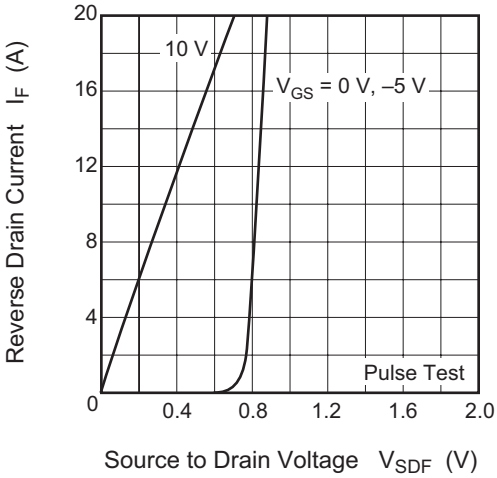
Dynamic Input Characteristics



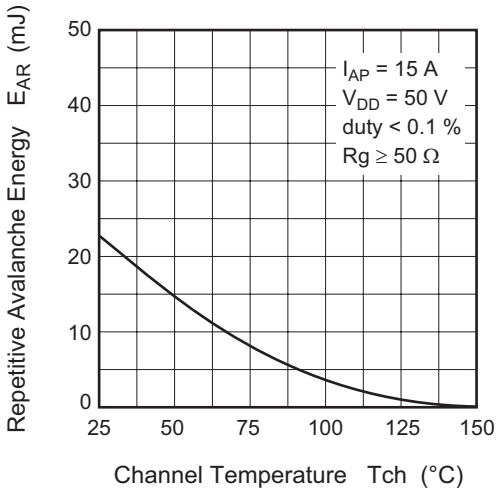
Switching Characteristics



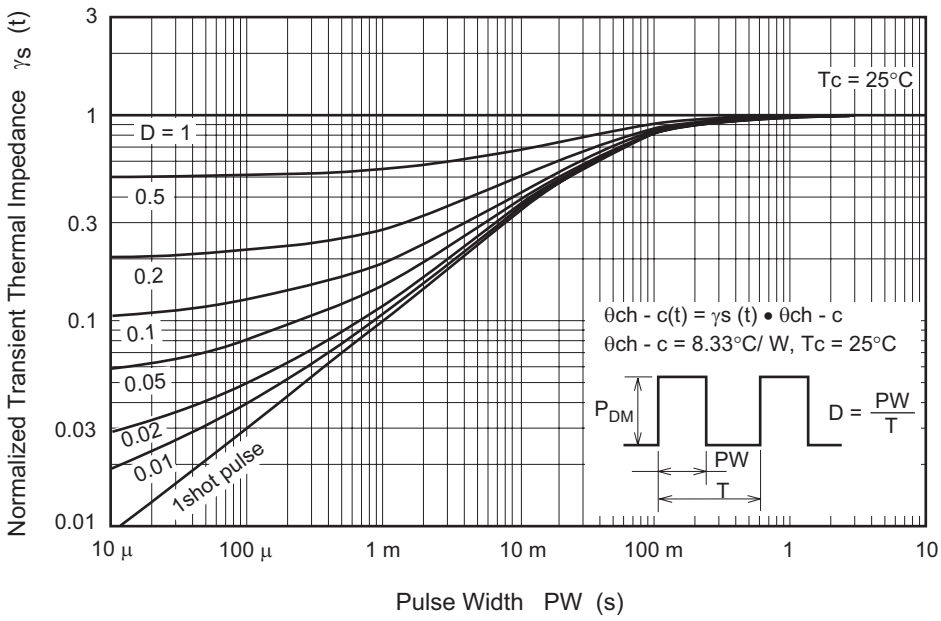
Reverse Drain Current vs.
Source to Drain Voltage



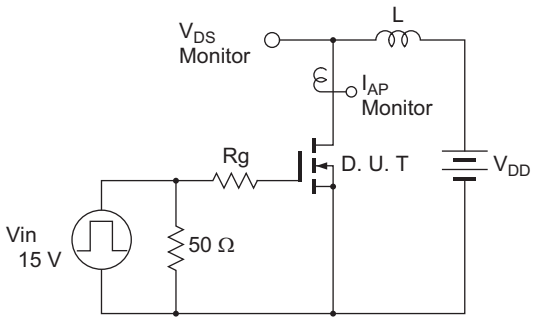
Maximum Avalanche Energy vs.
Channel Temperature Derating



Normalized Transient Thermal Impedance vs. Pulse Width

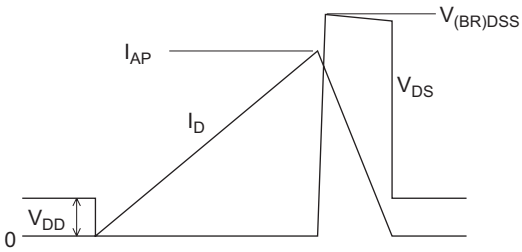


Avalanche Test Circuit

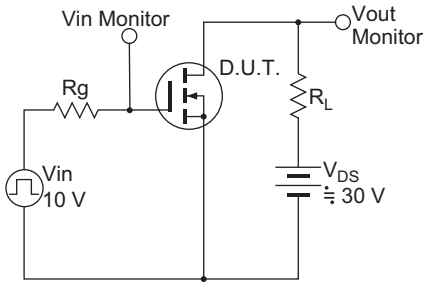


Avalanche Waveform

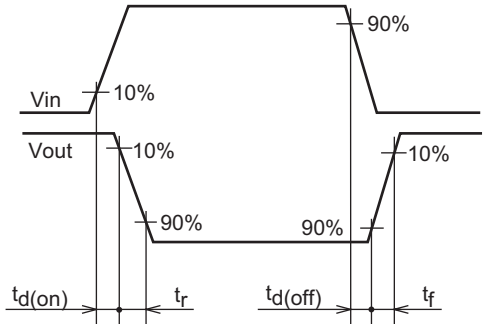
$$E_{AR} = \frac{1}{2} L \bullet I_{AP}^2 \bullet \frac{V_{DSS}}{V_{DSS} - V_{DD}}$$



Switching Time Test Circuit



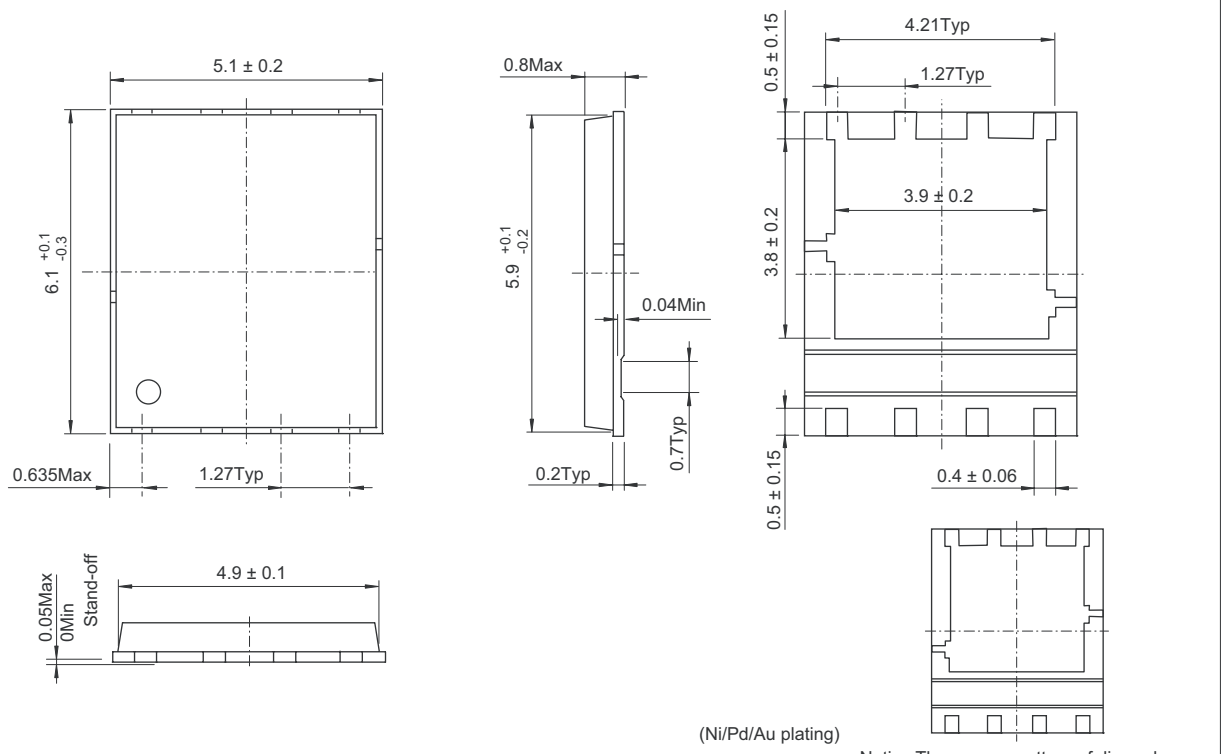
Switching Time Waveform



Package Dimensions

Package Name	JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
WPAK	–	PWSN0008DA-A	WPAKV	0.075g

Unit: mm



Ordering Information

Part No.	Quantity	Shipping Container
HAT2201WP-EL-E	2500 pcs	Taping

Renesas Technology Corp. Sales Strategic Planning Div. Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan

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Renesas Technology America, Inc.
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Tel: <1> (408) 382-7500, Fax: <1> (408) 382-7501

Renesas Technology Europe Limited
Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K.
Tel: <44> (1628) 585-100, Fax: <44> (1628) 585-900

Renesas Technology (Shanghai) Co., Ltd.
Unit 204, 205, AZIACenter, No.1233 Lujiazui Ring Rd, Pudong District, Shanghai, China 200120
Tel: <86> (21) 5877-1818, Fax: <86> (21) 6887-7858/7898

Renesas Technology Hong Kong Ltd.
7th Floor, North Tower, World Finance Centre, Harbour City, Canton Road, Tsimshatsui, Kowloon, Hong Kong
Tel: <852> 2265-6688, Fax: <852> 2377-3473

Renesas Technology Taiwan Co., Ltd.
10th Floor, No.99, Fushing North Road, Taipei, Taiwan
Tel: <886> (2) 2715-2888, Fax: <886> (2) 3518-3399

Renesas Technology Singapore Pte. Ltd.
1 Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632
Tel: <65> 6213-0200, Fax: <65> 6278-8001

Renesas Technology Korea Co., Ltd.
Kukje Center Bldg. 18th Fl., 191, 2-ka, Hangang-ro, Yongsan-ku, Seoul 140-702, Korea
Tel: <82> (2) 796-3115, Fax: <82> (2) 796-2145

Renesas Technology Malaysia Sdn. Bhd
Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No.18, Jln Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia
Tel: <603> 7955-9390, Fax: <603> 7955-9510

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